PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2736415

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHIUNG-HAN YEH	01/20/2014
MING-YUAN WU	01/17/2014
KONG-BENG THEI	01/17/2014
HARRY HAK-LAY CHUANG	01/20/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13794621

CORRESPONDENCE DATA

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Correspondence will be sent via US Mail when the email attempt is unsuccessful.
Correspondent Name: HAYNES AND BOONE, LLP - IP SECTION
Address Line 1: 2323 VICTORY AVENUE, SUITE 700
Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	2008-0233-D3/24061.2424
NAME OF SUBMITTER:	LYDIA EPPS-HILLIARD

Signature:	/LYDIA EPPS-HILLIARD/
Date:	02/21/2014

Total Attachments: 5
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Docket No.: 2008-0233-D3/ 24061.2424
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1) Chiung-Han Yeh of No. 214, Dawu Street, North District
Tainan City 704, Taiwan, R.O.C.

(2) Ming-Yuan Wu of 9F., No. 49, Jianzhong Road
East District, Hsin-Chu City 300
Taiwan, R.O.C.

(3) Kong-Beng Thei of No. 56, Nan-Kang 3rd Road
Pao-Shan Village, Hsin-Chu County
Taiwan, R.O.C.

(4) Harry Hak-Lay Chuang of 51 Paya LeBar
Crescent, Singapore 536191

(5) Mong-Song Liang of 2F., No. 16, Quanyuan Road
Beitou District, Taipei City 112
Taiwan, R.O.C.

have invented certain improvements in

INTEGRATING A FIRST CONTACT STRUCTURE IN A GATE LAST PROCESS

for which we have executed an application for Letters Patent of the United States of America, filed on March 11, 2013 and assigned application number 13/794,621; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue

patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chiung-Han Yeh

Residence Address: No. 214, Dawu Street, North District
Tainan City 704, Taiwan, R.O.C.

Dated: 1 . 20 . 2014

Chiung-Han Yeh
Inventor Signature

Inventor Name: Ming-Yuan Wu

Residence Address: 9F., No. 49, Jianzhong Road, East District
Hsin-Chu City 300, Taiwan, R.O.C.

Dated: ____________________

____
Inventor Signature

Inventor Name: Kong-Beng Thei

Residence Address: No. 56, Nan-Kang 3rd Road
Pao-Shan Village, Hsin-Chu County, Taiwan, R.O.C.

Dated: ____________________

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Inventor Signature

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Inventor Name: Chiung-Han Yeh

Residence Address: No. 214, Dawu Street, North District
Tainan City 704, Taiwan, R.O.C

Dated: ____________

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Inventor Signature

Inventor Name: Ming-Yuan Wu

Residence Address: 9F., No. 49, Jianzhong Road, East District
Hsin-Chu City 300, Taiwan, R.O.C

Dated: Jan 17, 14

Ming-Yuan Wu
Inventor Signature

Inventor Name: Kong-Beng Thei

Residence Address: No. 56, Nan-Kang 3rd Road
Pao-Shan Village, Hsin-Chu County, Taiwan, R.O.C.

Dated: ____________

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Inventor Name: Chiung-Han Yeh

Residence Address: No. 214, Dawu Street, North District
Tainan City 704, Taiwan, R.O.C

Dated:______________

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Inventor Signature

Inventor Name: Ming-Yuan Wu

Residence Address: 9F., No. 49, Jianzhong Road, East District
Hsin-Chu City 300, Taiwan, R.O.C

Dated:______________

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Inventor Signature

Inventor Name: Kong-Beng Thei

Residence Address: No. 56, Nan-Kang 3rd Road
Pao-Shan Village, Hsin-Chu County, Taiwan, R.O.C.

Dated: 1/17/2014.

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Inventor Signature

Inventor Name: Harry Hak-Lay Chuang

Residence Address: 51 Paya LeBar, Crescent, Singapore 536191

Dated: 2014-1-20

Inventor Signature

Inventor Name: Mong-Song Liang

Residence Address: 2F., No. 16, Quanyuan Road, Beitou District, Taipei City 112
Taiwan, R.O.C

Dated:____________________

Inventor Signature
